

## SPECIFICATIONS

# PXIe-5774

## 12-Bit, 6.4 GS/s, DC-Coupled, 2-Channel PXI FlexRIO Digitizer

This document lists the specifications for the PXIe-5774. Specifications are subject to change without notice. For the most recent device specifications, refer to [ni.com/support](http://ni.com/support).

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## Definitions

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*Warranted* specifications describe the performance of a model under stated operating conditions and are covered by the model warranty.

*Characteristics* describe values that are relevant to the use of the model under stated operating conditions but are not covered by the model warranty.

- *Typical* specifications describe the performance met by a majority of models.
- *Nominal* specifications describe an attribute that is based on design, conformance testing, or supplemental testing.
- *Measured* specifications describe the measured performance of a representative model.

Specifications are *Typical* unless otherwise noted.

## Conditions

Specifications are valid under the following conditions unless otherwise noted.

- Ambient temperature of  $23\text{ }^{\circ}\text{C} \pm 5\text{ }^{\circ}\text{C}$
- Installed in chassis with slot cooling capacity  $\geq 58\text{ W}$

## Digital I/O

Connector	Molex™ Nano-Pitch I/O™
5.0 V Power	$\pm 5\%$ , 50 mA maximum, nominal

**Table 1.** Digital I/O Signal Characteristics

Signal	Type	Direction
MGT Tx± <0..3>	Xilinx UltraScale GTH	Output
MGT Rx± <0..3>	Xilinx UltraScale GTH	Input
DIO <0..7>	Single-ended	Bidirectional
5.0 V	DC	Output
GND	Ground	—

## Digital I/O Single-Ended Channels

Number of channels	8
Signal type	Single-ended
Voltage families	3.3 V, 2.5 V, 1.8 V, 1.5 V, 1.2 V
Input impedance	100 k $\Omega$ , nominal
Output impedance	50 $\Omega$ , nominal
Direction control	Per channel

Minimum required direction change latency	200 ns
Maximum output toggle rate	60 MHz with 100 $\mu$ A load, nominal

**Table 2.** Digital I/O Single-Ended DC Signal Characteristics<sup>1</sup>

Voltage Family	V <sub>IL</sub>	V <sub>IH</sub>	V <sub>OL</sub> (100 $\mu$ A load)	V <sub>OH</sub> (100 $\mu$ A load)	Maximum DC Drive Strength
3.3 V	0.8 V	2.0 V	0.2 V	3.0 V	24 mA
2.5 V	0.7 V	1.6 V	0.2 V	2.2 V	18 mA
1.8 V	0.62 V	1.29 V	0.2 V	1.5 V	16 mA
1.5 V	0.51 V	1.07 V	0.2 V	1.2 V	12 mA
1.2 V	0.42 V	0.87 V	0.2 V	0.9 V	6 mA

## Digital I/O High-Speed Serial MGT<sup>2</sup>

Data rate	500 Mbps to 16.375 Gbps, nominal
Number of Tx channels	4
Number of Rx channels	4
I/O AC coupling capacitor	100 nF

### MGT TX $\pm$ Channels

Minimum differential output voltage <sup>3</sup>	170 mV pk-pk into 100 $\Omega$ , nominal
I/O coupling	AC-coupled with 100 nF capacitor

### MGT RX $\pm$ Channels

Differential input voltage range	
$\leq$ 6.6 Gb/s	150 mV pk-pk to 2000 mV pk-pk, nominal
$>$ 6.6 Gb/s	150 mV pk-pk to 1250 mV pk-pk, nominal
Differential input resistance	100 $\Omega$ , nominal
I/O coupling	DC-coupled, requires external capacitor $\Delta$

<sup>1</sup> Voltage levels are guaranteed by design through the digital buffer specifications.

<sup>2</sup> For detailed FPGA and High-Speed Serial Link specifications, refer to Xilinx documentation.

<sup>3</sup> 800 mV pk-pk when transmitter output swing is set to the maximum setting.

# Reconfigurable FPGA

PXIe-5774 modules are available with multiple FPGA options. The following table lists the FPGA specifications for the PXIe-5774 FPGA options.

**Table 3.** Reconfigurable FPGA Options

	<b>KU040</b>	<b>KU060</b>
LUTs	242,200	331,680
DSP48 slices (25 × 18 multiplier)	1,920	2,760
Embedded Block RAM	21.1 Mb	38.0 Mb
Data Clock Domain	200 MHz, 16 samples per cycle per channel (dual channel mode), 32 samples per cycle (single channel mode)	
Timebase reference sources	PXI Express 100 MHz (PXIe_CLK100)	
Data transfers	DMA, interrupts, programmed I/O, multi-gigabit transceivers	
Number of DMA channels	60	



**Note** The Reconfigurable FPGA Options table depicts the total number of FPGA resources available on the part. The number of resources available to the user is slightly lower, as some FPGA resources are consumed by board-interfacing IP for PCI Express, device configuration, and various board I/O. For more information, contact NI support.

## Onboard DRAM

Memory size	4 GB (2 banks of 2 GB)
DRAM clock rate	1064 MHz
Physical bus width	32 bit
LabVIEW FPGA DRAM clock rate	267 MHz
LabVIEW FPGA DRAM bus width	256 bit per bank
Maximum theoretical data rate	17 GB/s (8.5 GB/s per bank)

# Analog Input

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## General Characteristics

Number of channels	2, single-ended, simultaneously sampled
Connector type	SMA
Input impedance	50 $\Omega$ , nominal
Input coupling	DC
Sample Clock	
Internal Sample Clock <sup>4</sup>	3.2 GHz
External Sample Clock <sup>4</sup>	3.2 GHz
Sample Rate	
Dual channel mode	3.2 GS/s per channel
Single channel mode	6.4 GS/s
Analog-to-digital converter (ADC)	ADC12DJ3200, 12-bit resolution

## Typical Specifications

Full-scale input ranges	200 mV pk-pk 1 V pk-pk
Gain accuracy	
200 mV range	$\pm 1.47\%$
1 V range	$\pm 1.44\%$
DC offset	
200 mV range	$\pm 0.628$ mV
1 V range	$\pm 1.269$ mV
Vertical offset range	$\pm 0.5$ full-scale, nominal
Bandwidth (-3 dB) <sup>5</sup>	
-01 variant	200 mV range: 3.00 GHz 1 V range: 2.85 GHz
-02 variant	200 mV range: 1.63 GHz 1 V range: 1.62 GHz

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<sup>4</sup> In single channel mode the ADC cores are interleaved for an aggregate sample rate of 6.4 GS/s.

<sup>5</sup> Normalized to 10 MHz.

**Table 4.** Single-Tone Spectral Performance, Dual Channel Mode, 1 V range, -01 Variant

	Input Frequency			
	99.9 MHz	399 MHz	999 MHz	1.999 GHz
SNR <sup>6</sup> (dBFS)	54.7	54.4	53.9	52.8
SINAD <sup>6</sup> (dBFS)	54.4	53.8	53.3	52.4
SFDR (dBc)	-65.2	-61.1	-60.3	-63.2
ENOB <sup>7</sup> (bits)	8.7	8.6	8.5	8.4

**Table 5.** Single-Tone Spectral Performance, Single Channel Mode, 1 V range, -01 Variant<sup>8</sup>

	Input Frequency			
	99.9 MHz	399 MHz	999 MHz	1.999 GHz
SNR <sup>6</sup> (dBFS)	54.0	53.9	52.8	50.1
SINAD <sup>6</sup> (dBFS)	53.9	53.4	52.2	50.0
SFDR (dBc)	-61.3	-60.9	-58.4	-52.3
ENOB <sup>7</sup> (bits)	8.7	8.6	8.4	8.0

**Table 6.** Single-Tone Spectral Performance, Dual Channel Mode, 200 mV range, -01 Variant

	Input Frequency			
	99.9 MHz	399 MHz	999 MHz	1.999 GHz
SNR <sup>6</sup> (dBFS)	52.0	52.0	51.7	50.9
SINAD <sup>6</sup> (dBFS)	51.9	51.8	51.4	50.7
SFDR (dBc)	-65.1	-61.7	-62	-64.4
ENOB <sup>7</sup> (bits)	8.3	8.3	8.2	8.1

<sup>6</sup> Measured with a -1 dBFS signal and corrected to full-scale. 3.2 kHz resolution bandwidth.

<sup>7</sup> Calculated from SINAD and corrected to full scale.

<sup>8</sup> Measured using channel A10. Spectral performance may be degraded using channel A11.

**Table 7.** Single-Tone Spectral Performance, Single Channel Mode, 200 mV range, -01 Variant<sup>8</sup>

	Input Frequency			
	99.9 MHz	399 MHz	999 MHz	1.999 GHz
SNR <sup>6</sup> (dBFS)	51.0	51.0	50.4	48.9
SINAD <sup>6</sup> (dBFS)	51.0	50.8	50.2	48.9
SFDR (dBc)	-57.8	-58.8	-58.4	-53.3
ENOB <sup>7</sup> (bits)	8.2	8.1	8.0	7.8

**Table 8.** Noise Spectral Density, 1 V Range, -01 Variant<sup>9</sup>

Mode	$\frac{nV}{\sqrt{Hz}}$	$\frac{dBm}{Hz}$	$\frac{dBFS}{Hz}$
Dual channel	15.3	-143.3	-147.3
Single channel	10.2	-146.8	-150.8

**Table 9.** Noise Spectral Density, 200 mV Range, -01 Variant<sup>9</sup>

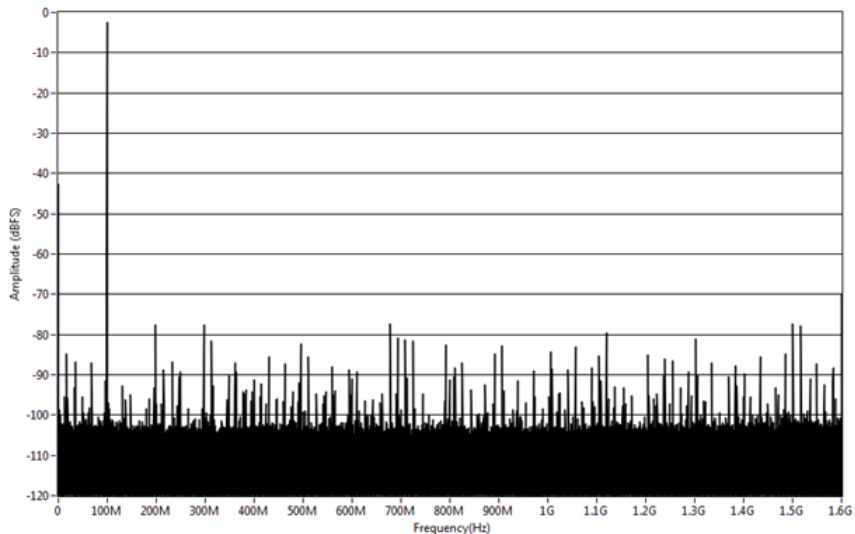
Mode	$\frac{nV}{\sqrt{Hz}}$	$\frac{dBm}{Hz}$	$\frac{dBFS}{Hz}$
Dual channel	4.3	-154.3	-144.3
Single channel	3.1	-157.1	-147.1



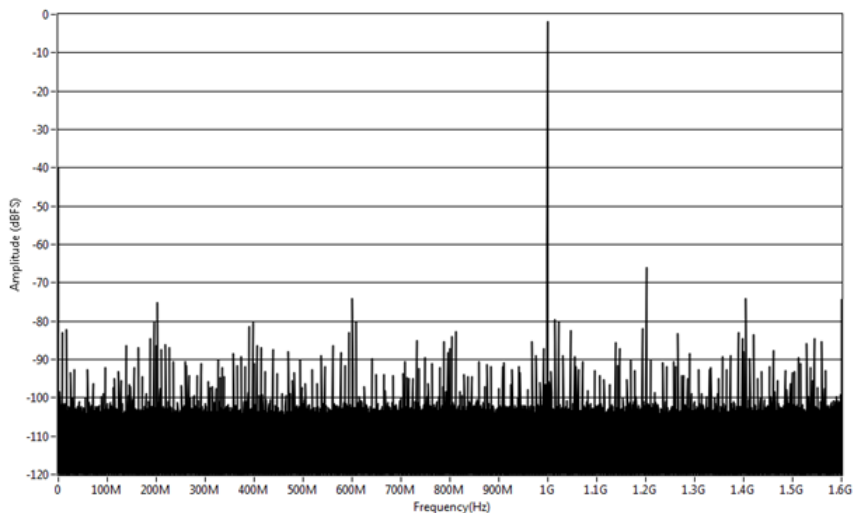
**Note** Noise spectral density is verified using a 50  $\Omega$  terminator connected to AI0. Noise Spectral density may be degraded using channel AI1.

<sup>9</sup> Excludes fixed interleaving spurs.

**Figure 1.** Single Tone Spectrum (Dual Channel Mode, 99MHz, -1 dBFS, 1 V Range, 3.2 kHz RBW, -01 Variant), Measured

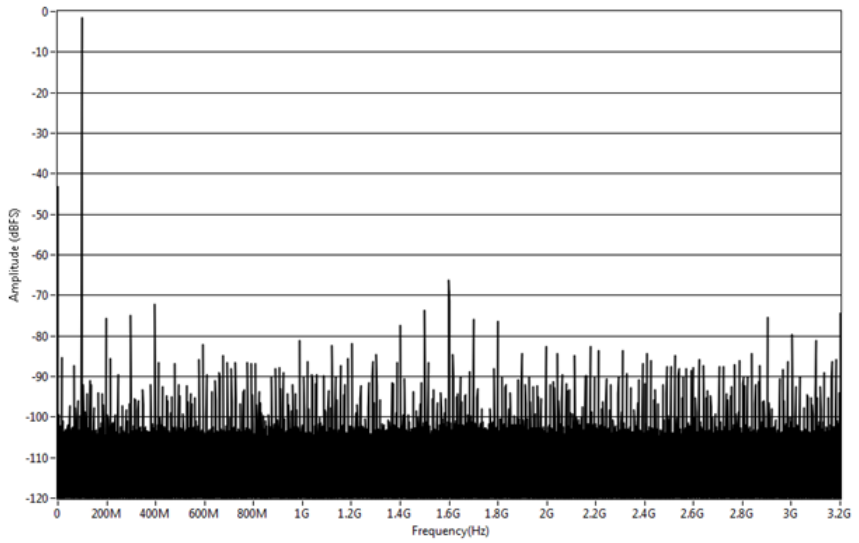


**Figure 2.** Single Tone Spectrum (Dual Channel Mode, 999 MHz, -1 dBFS, 1 V Range, 3.2 kHz RBW, -01 Variant), Measured

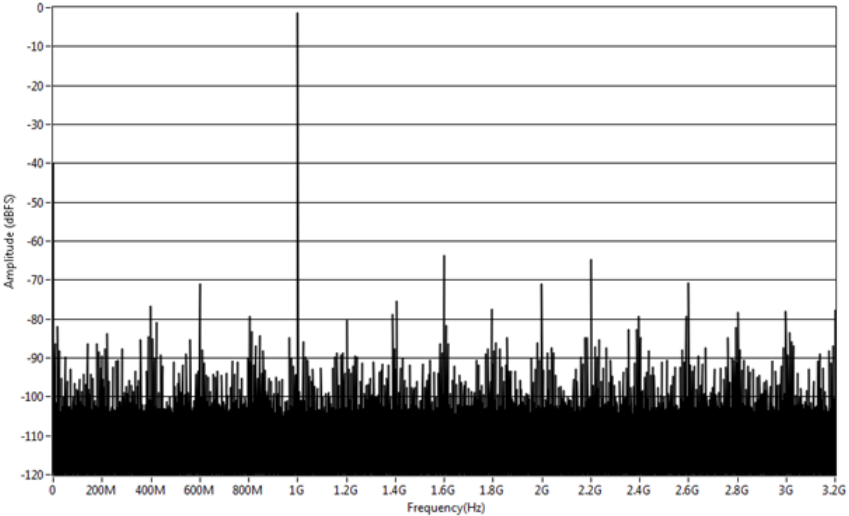




**Figure 3.** Single Tone Spectrum (Single Channel Mode, 99 MHz, -1 dBFS, 1 V Range, 3.2 kHz RBW, -01 Variant), Measured



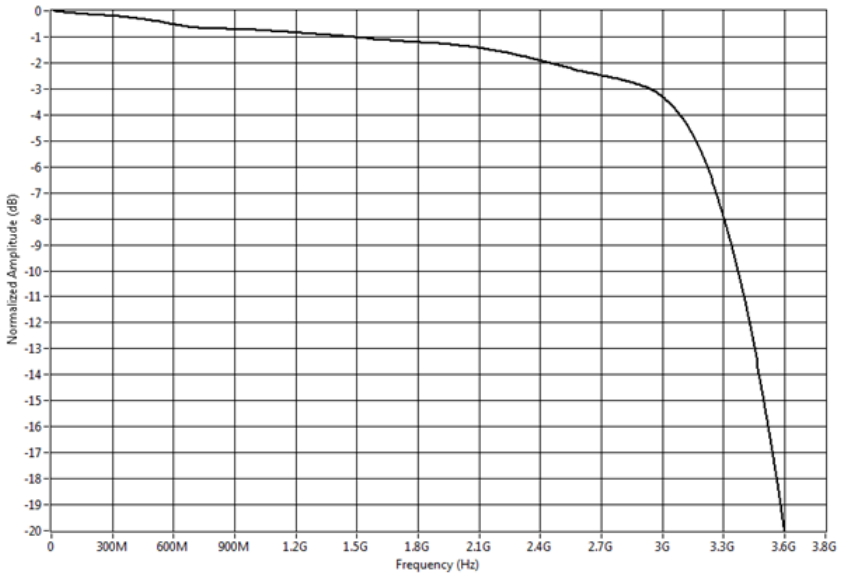
**Figure 4.** Single Tone Spectrum (Single Channel Mode, 999 MHz, -1 dBFS, 1 V Range, 3.2 kHz RBW, -01 Variant), Measured



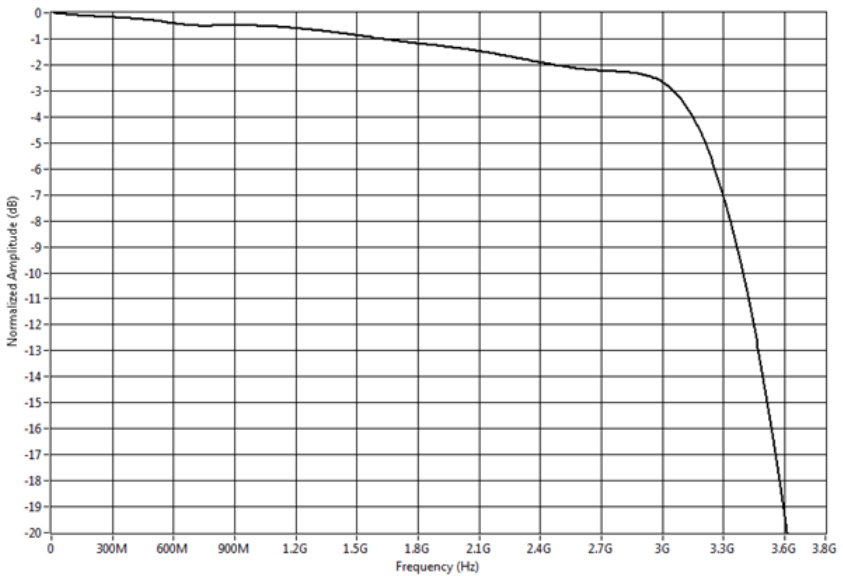
Channel-to-channel crosstalk, measured

99.9 MHz	-94.1 dB
399 MHz	-85.6 dB
999 MHz	-82.5 dB
1.59 GHz	-75.6 dB
1.99 GHz	-72.2 dB

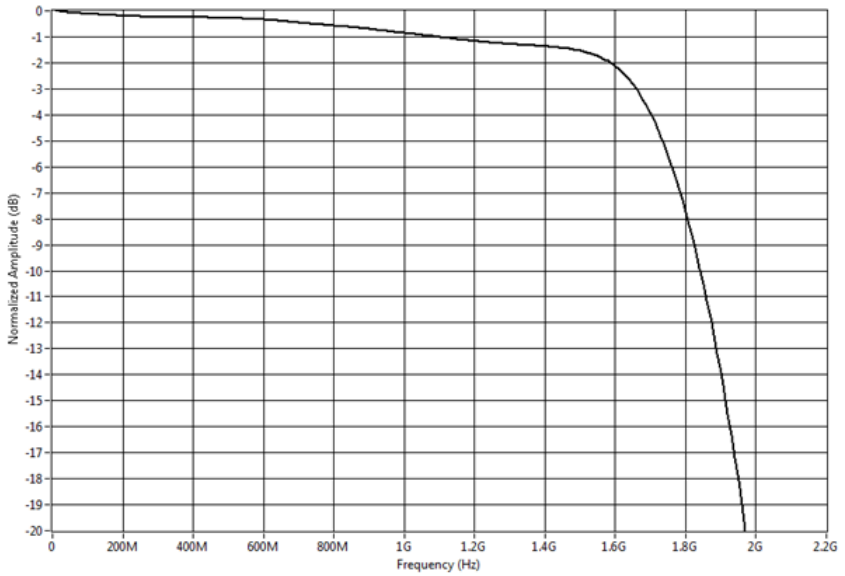
**Figure 5.** Analog Input Frequency Response (1 V Range, -01 Variant), Measured



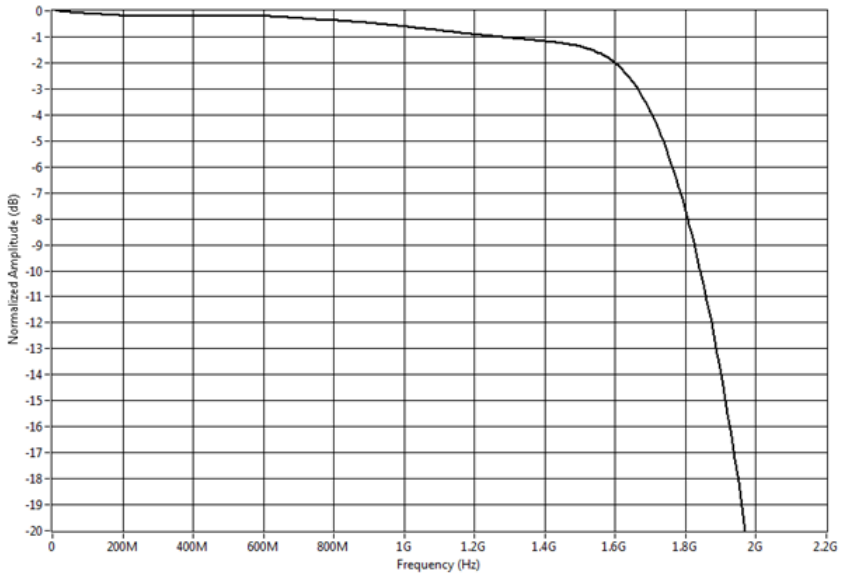
**Figure 6.** Analog Input Frequency Response (200 mV Range, -01 Variant), Measured



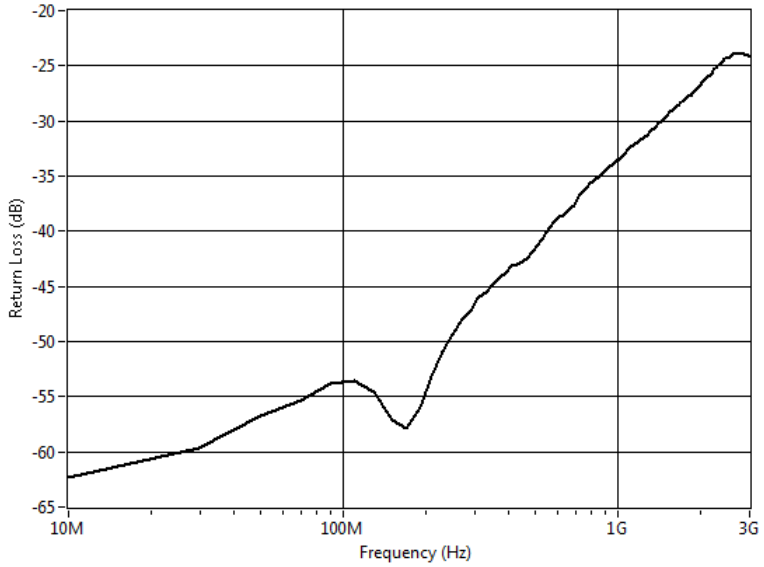
**Figure 7.** Analog Input Frequency Response (1 V Range, -02 Variant), Measured



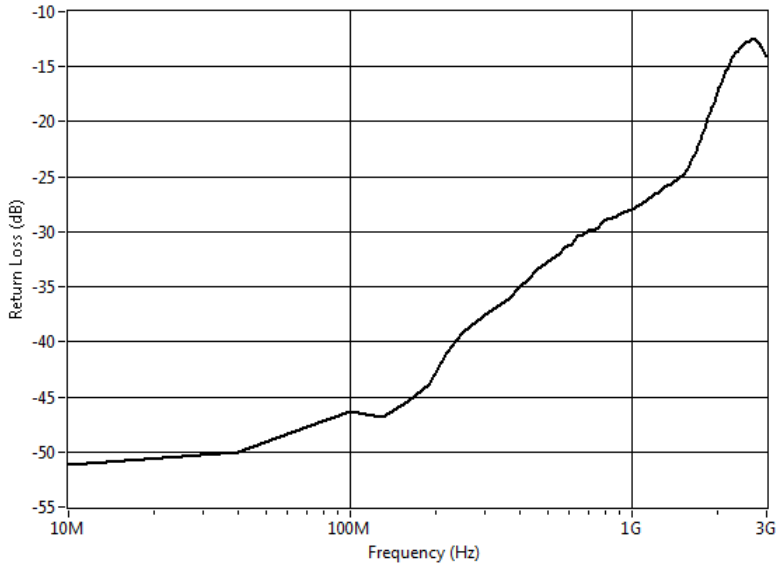
**Figure 8.** Analog Input Frequency Response (200 mV Range, -02 Variant), Measured



**Figure 9.** Input Return Loss (1 V Range), Measured



**Figure 10.** Input Return Loss (200 mV Range), Measured



# REF/CLK IN

Connector type	SMA
Input impedance	50 $\Omega$
Input coupling	AC
Input voltage range	0.35 V pk-pk to 3.5 V pk-pk
Absolute maximum voltage	$\pm 12$ V DC, 5 V pk-pk AC
Duty cycle	45% to 55%
Onboard reference timebase stability	$\pm 0.5$ ppm
Sample Clock jitter <sup>10</sup>	85 fs RMS, measured

**Table 10.** Clock Configuration Options

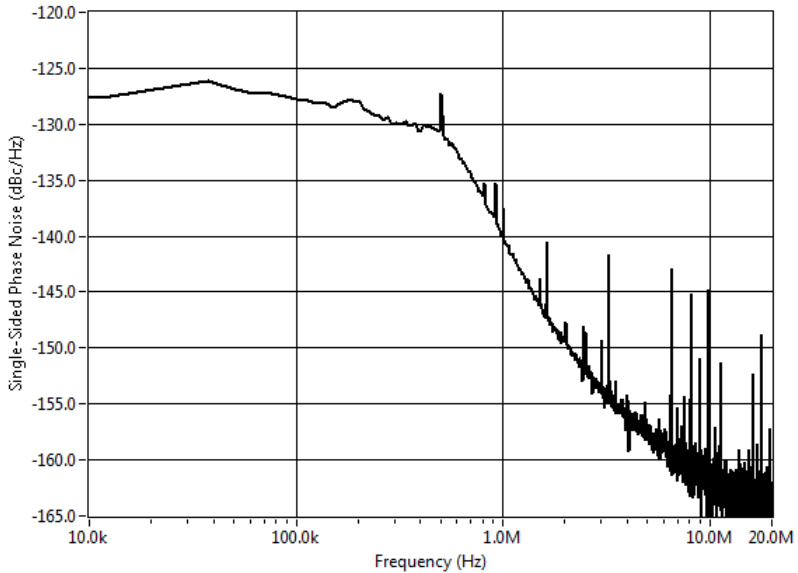
Clock Configuration	External Clock Frequency	Description
Internal Reference Clock <sup>11</sup>	-	The internal Sample Clock locks to an onboard voltage-controlled temperature compensated crystal oscillator (VCTCXO).
Internal PXI_CLK10	10 MHz	The internal Sample Clock locks to the PXI 10 MHz Reference Clock, which is provided through the FPGA baseboard.
External Reference Clock (REF/CLK IN)	10 MHz <sup>12</sup>	The internal Sample Clock locks to an external Reference Clock, which is provided through the REF/CLK IN front panel connector.
External Sample Clock (REF/CLK IN)	3.2 GHz	An external Sample Clock can be provided through the REF/CLK IN front panel connector.

<sup>10</sup> Integrated from 3.2 kHz to 20 MHz. Includes the effects of the converter aperture uncertainty and the clock circuitry jitter. Excludes trigger jitter.

<sup>11</sup> Default clock configuration.

<sup>12</sup> The external Reference Clock must be accurate to  $\pm 25$  ppm.

**Figure 11.** Phase Noise with 800 MHz Input Tone, Measured



## Analog IN Trigger

Connector type	SMA
Input impedance	50 $\Omega$ , nominal
Input coupling	DC
Input voltage range	$\pm 5$ V
Comparator threshold resolution	12 bits
Minimum pulse width	5 ns
Absolute maximum voltage	$\pm 6$ V

## Digital OUT Trigger

Connector type	SMA
Input impedance	50 $\Omega$ , nominal
Input coupling	DC
Logic type	3.3 V CMOS

Maximum current drive	24 mA
Update rate resolution	5 ns
Jitter	3.2 ps rms, measured

## Bus Interface

Form factor	PCI Express Gen-3 x8
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## Maximum Power Requirements



**Note** Power requirements are dependent on the contents of the LabVIEW FPGA VI used in your application.

+3.3 V	3 A
+12 V	4 A
Maximum total power	58 W

## Physical

Dimensions (not including connectors)	2.0 cm × 13.0 cm × 21.6 cm (0.8 in. × 5.1 in. × 8.5 in.)
Weight	500 g (17.6 oz)

## Environment

Maximum altitude	2,000 m (800 mbar) (at 25 °C ambient temperature)
Pollution Degree	2

Indoor use only.

## Operating Environment

Ambient temperature range	0 °C to 55 °C <sup>13</sup>
Relative humidity range	10% to 90%, noncondensing

<sup>13</sup> The PXIe-5774 requires a chassis with slot cooling capacity  $\geq 58$  W. Not all chassis with slot cooling capacity  $\geq 58$  W can achieve this ambient temperature range. Refer to the [PXI Chassis Manual](#) for specifications to determine the ambient temperature ranges your chassis can achieve.



## Storage Environment

Ambient temperature range	-40 °C to 71 °C
Relative humidity range	5% to 95%, noncondensing

## Shock and Vibration

Operating shock	30 g peak, half-sine, 11 ms pulse (Tested in accordance with IEC 60068-2-27. Meets MIL-PRF-28800F Class 2 limits.)
Random vibration	
Operating	5 Hz to 500 Hz, 0.3 g <sub>rms</sub> (Tested in accordance with IEC 60068-2-64.)
Nonoperating	5 Hz to 500 Hz, 2.4 g <sub>rms</sub> (Tested in accordance with IEC 60068-2-64. Test profile exceeds the requirements of MIL-PRF-28800F, Class 3.)

## TCLK Specifications

You can use the NI TCLK synchronization method and the NI-TCLK driver to align the Sample Clocks on any number of supported devices, in one or more chassis. For more information about TCLK synchronization, refer to the *NI-TCLK Synchronization Help* within the *FlexRIO Help*. For other configurations, including multichassis systems, contact NI Technical Support at [ni.com/support](http://ni.com/support).

## Intermodule Synchronization Using NI-TCLK for Identical Modules

Synchronization specifications are valid under the following conditions:

- All modules are installed in one PXI Express chassis.
- The NI-TCLK driver is used to align the Sample Clocks of each module.

- All parameters are set to identical values for each module.
- Modules are synchronized without using an external Sample Clock.



**Note** Although you can use NI-TClk to synchronize non-identical modules, these specifications apply only to synchronizing identical modules.

Skew <sup>14</sup>	80 ps, measured
Skew after manual adjustment	≤10 ps, measured
Sample Clock delay/adjustment	0.4 ps

<sup>14</sup> Caused by clock and analog delay differences. No manual adjustment performed. Tested with a PXIe-1085 chassis with a 24 GB backplane with a maximum slot to slot skew of 100 ps. Measured at 23 °C.

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